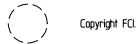


Ø.760 SOLDER BALLS  
NOTE 2.

⊕ Ø.30 X Y

∕ .203

mat'l. code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
titr	ec'n no	dr	date	tolerances unless otherwise specified			MEG-ARRAY
N	v06-0560	LP	2006/07/18	angles	Xx3	MM	title
-	-	-	-		XXX-B		4mm RECPT. ASSY
H	v00181	HLJ	7/5/00	0° ±2'	XXXX-051	scale 3:1	10 X 40= 400 POS.
J	v20006	DRW	1/3/2	dr	D WAUGHEN	11.26.97	dwg no
K	v03-0679	DAI	6/19/03	engr	T LEMKE	11.26.97	sheet 1 of 3
L	v04-0940	VS	10/18/04	chr	T LEMKE	11.26.97	size
M	v05-1071	DAI	12/21/05	appd	T LEMKE	11.26.97	A4
sheet index	revision sheet	N	N	N			74221
		1	2	3			type
							CUSTOMER Drawing

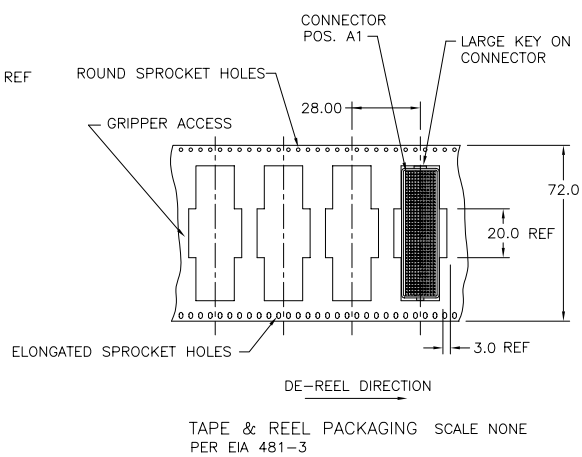
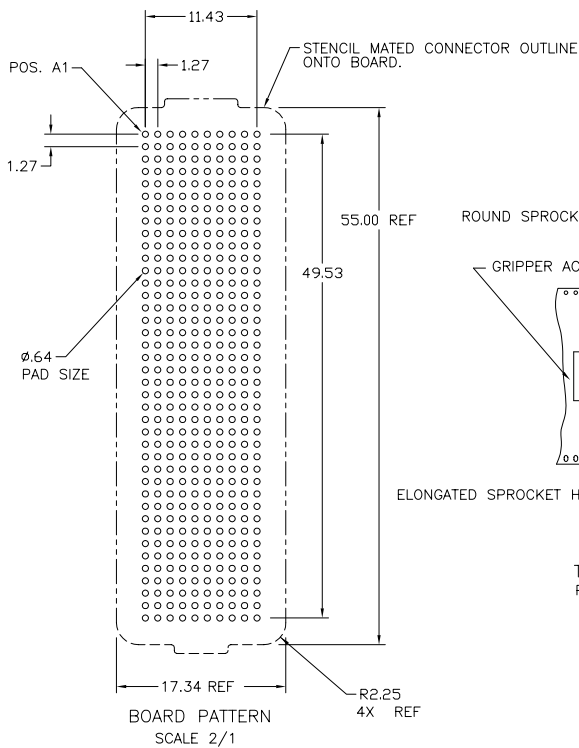
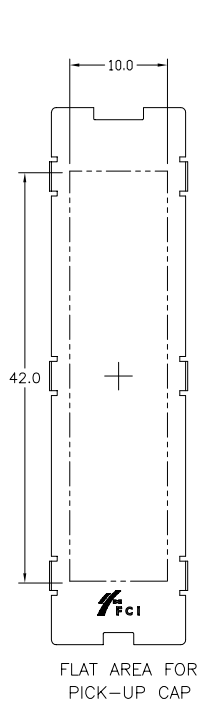


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mat'l. code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family	MEG-ARRAY
titr	ecm no	dir	date	tolerances unless otherwise specified		MM	title	4mm RECP. ASSY
N				angles	xxx3	scale	2:1	10x40= 400 POS.
				or ±2"	xxx3			
				appd	T LEMKE			
				chr	T LEMKE			
				engr	T LEMKE			
				dr	D WAUGHEN			
sheet index	revision sheet							

PDM: Rev:N STATUS Released Printed: Oct 21, 2010

form A4mmXLC

1

2

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4

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74221-001	YES	15u" (.38um) Au OVER Ni	SnPb
74221-001LF			SnAgCu LEAD FREE (6)(7)
74221-101	YES	30 u" (.76um) Au OVER Ni	SnPb
74221-101LF			SnAgCu LEAD FREE (6)(7)
74221-201	YES	SEE NOTE 5.	SnPb
74221-201LF			SnAgCu LEAD FREE (6)(7)

NOTES:

1. MAT'L:

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET3)  
 SOLDER BALL: (SEE TABLE ON SHEET3)  
 EUTECTIC SnPb OR LEAD FREE  
 95.5Sn/4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.

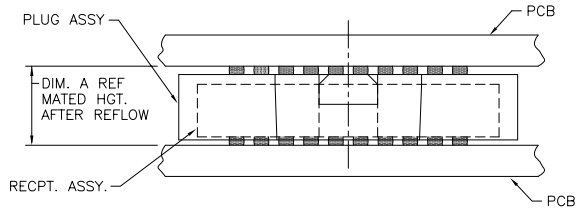
3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

4. NO TIN/LEAD OR FLUX ABOVE TERMINAL SHOULDER.

5. PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



DIM. A	PLUG ASSY P/N	RECEPT. ASSY P/N
4.0	84740	74221
10.0	84520	74221

MATED HEIGHT AFTER REFLOW IS BASED ON  $\phi$  .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

mat'l code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family	MEG-ARRAY
litr	ecrn no	dir	date	tolerances unless otherwise specified		MM	title	4mm RECEPT. ASSY
N				angles	Xx3	scale	10x40= 400 POS.	
				or ±2"	XXX-B	2:1	sheet 3 of 3	size A4
				dr	D WAUGHEN 11.26.97		dwg no	74221
				engr	T LEMKE 11.26.97		type	CUSTOMER Drawing
				chr	T LEMKE 11.26.97			
				appd	T LEMKE 11.26.97			
sheet index	revision sheet							